

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A semiconductor wafer clean transfer device which automatically transfers a sheet-like electronic component accommodated in a cassette in clean air, comprising:

a casing within which the cassette is opened;

a fan/filter unit provided on a ceiling of the casing that blows clean air into the casing;

a conveying robot provided in the casing that automatically transfers the semiconductor wafer between predetermined positions;

a filter provided in the fan/filter unit that removes 99.999% or above of particulates of 0.1 μm or above; and

a first floor provided in the casing and horizontally arranged on a lower side of an arm of the conveying robot at a middle height part of the conveying robot and through which air can pass between an upper side of the first floor and a lower side of the first floor,

wherein the casing defines a first chamber between the first floor and the fan/filter unit, and a second chamber between the first floor and a bottom part of the casing through which air can pass between the second chamber and an outside of the bottom part of the casing, and

the conveying robot comprises:

a dust generation preventing seal structure provided to an articulated part of the arm; and

a body which supports the arm and which has a vent hole arranged on a lower side of the first ~~floor~~ floor;

a body cover disposed on a side surface of the body; and

a base cover disposed at the base of the body;

wherein a gap is formed on an inner side of a lower portion of the body cover
between the body cover and the base cover so that air is upwardly taken in and from which air
in the body is downwardly discharged to the second chamber upon a descending operation of
the body.

2. (Previously Presented) The semiconductor wafer clean transfer device
according to claim 1, further comprising:

a door provided on a wall of the first chamber that moves up and down; and

a door passage for the door, provided on the second chamber side and covered
with a partition,

wherein a part of clean air which flows into the second chamber from the first
chamber is directly discharged to the casing bottom part through the door passage.

3. (Previously Presented) The semiconductor wafer clean transfer device
according to claim 1, wherein a gap is provided between a door frame part provided on the
wall of the first chamber and the door set so as to be adjacent thereto, and/or between the door
frame part and the cassette, and between the first floor and a body of the conveying robot, and

a width of the gap is not less than 1 mm and not more than 30 mm.

4. (Canceled)

5. (Currently Amended) The semiconductor wafer clean transfer device
according to claim 1, further comprising a second floor provided in the casing and
horizontally arranged in the vicinity of a base of the conveying robot,

wherein the second floor changes a degree of opening of the casing bottom
part with respect to the outside, ~~and through~~ through which air can pass between an upper

side and a lower side of the second ~~floor~~ floor, and the degree of opening of the casing bottom is larger than that of the first floor.

6. (Currently Amended) The semiconductor wafer clean transfer device according to ~~claim 1~~, claim 5, wherein an open space in the first floor is not less than 5% and not more than 50% of the total area of the first floor, and an open space in the casing bottom part is not less than 5% and not more than 70% of the total area of the casing bottom.

7. (Previously Presented) The semiconductor wafer clean transfer device according to claim 6, wherein an internal pressure of the first chamber is higher than an internal pressure of the second chamber, and

an internal pressure of the second chamber is not less than 0.1 Pa as a gauge pressure higher than a gauge pressure of an outside of the casing.

8. (Previously Presented) The semiconductor wafer clean transfer device according to claim 1, wherein the number of times of ventilation of the first chamber is not less than 5 per minute and not more than 45 per minute.

9. (Previously Presented) The semiconductor wafer clean transfer device according to claim 1, wherein a blowing speed of the clean air into the first chamber from the fan/filter unit is not less than 0.1 m/second to not more than 0.65 m/second.

10. (Previously Presented) The semiconductor wafer clean transfer device according to claim 1, wherein one wall of the casing has an opening part which opens to at least one of the first chamber and the second chamber,

a degree of opening of the opening part with respect to the one wall is not more than 20%,

an internal pressure of the first chamber is not less than 0.1 Pa as a gauge pressure higher than a gauge pressure of an outside of the casing, and

the number of times of ventilation of the first chamber is not less than 10 per minute and not more than 45 per minute.

11. (Previously Presented) A semiconductor wafer manufacturing system comprising the semiconductor wafer clean transfer device according to claim 1.

12. (Previously Presented) The semiconductor wafer clean transfer device according to claim 1, wherein the vent hole comprises a downward gap between a body cover and a base cover of the conveying robot.